Product Information Sheet

EPO-TEK® H75

Date:	September 2017	
Rev:	III	
No. of Components:	Two	
Mix Ratio by Weight:	100 : 3.3	
Specific Gravity:	Part A: 2.27	Part B: 1.02
Pot Life:	3 Hours	
Shelf Life- Bulk:	One year at room temperature	

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
150°C / 5 Minutes
100°C / 30 Minutes
80°C / 2 Hours

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.
- Syringe packaging will impact initial viscosity and effective pot life, potentially beyond stated parameters.

Product Description: A two component, high Tg, thermally conductive, electrically insulating epoxy designed for semiconductor packaging including heat sinking, hermetic sealing, and opto-electronic assemblies. It may be considered a higher viscosity alternative to EPO-TEK® H74.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results. Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Part A: Grey	Part B: Amber
* Consistency:	Thick paste	
* Viscosity (23°C) @ 0.5 rpm:	300,000-400,000	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 100	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	29	x 10^{-6} in/in°C
Above Tg:	90	x 10^{-6} in/in°C
Shore D Hardness:	95	
Lap Shear @ 23°C:	1,892	psi
Die Shear @ 23°C:	≥ 20	Kg 7,112 psi
Degradation Temp:	416	°C
Weight Loss:		
@ 200°C:	< 0.05	%
@ 250°C:	0.08	%
@ 300°C:	0.20	%
Suggested Operating Temperature:	< 350	°C (Intermittent)
Storage Modulus:	945,531	psi
* Particle Size:	≤ 50	microns

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	0.7	W/mK
Volume Resistivity @ 23°C:	≥ 2 x 10^{12}	Ohm-cm
Dielectric Constant (1KHz):	5.37	
Dissipation Factor (1KHz):	0.008	

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